

<b>ENGINEERING DEPT.</b>		<b>PRODUCT SPECIFICATION</b> <b>General Plating Specification</b>	<b>SPEC.NO.: SPPT001G</b>
<b>REVISION</b> S	ECNT116112		<b>PAGE: 1/3</b>

1. SCOPE:

This plating specification contains plating standard and Solderability test methods of CviLux's subject connectors of connectors. The specification is composed of the following sections:

<u>PARAGRAPH</u>	<u>TITLE</u>
1.0	Scope
2.0	Applicable Document
3.0	Plating Standard Tables
4.0	Solder ability

2. The following document of the issue in effect on the date of latest revision of this specification, shall from a part of this specification to the extent specified herein:

**MILITARY SPECIFICATIONS**

MIL - G - 45204	Gold plating, Electrodeposit
MIL - T - 10727	Tin plating

**MILITARY STANDARDS**

MIL - STD - 105	Sampling procedures and tables for inspection by attributes
MIL - STD - 202	Test methods for electrical and electrical components
MIL - STD - 1344	Test methods for electrical connector
MIL - STD - 202	Solder ability test



REVIEWED : Eisley APPROVED : Sun VERIFIED : Karen .

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### 3. PLATING STANDARDS

The crimp clip terminals, square pins, round pins, and solder tail contacts shall be plated and meet following requirement, thickness of Tinplating layer is listed in TABLE- 1 and thickness of Gold plating layer is listed in TABLE- 2. Nickel shall be plated overall

**TABLE- 1 (Tin-Plated)**

Plating Code	Top Plating Thickness		Under Plating Thickness		Area	Match Type
	Min.	Max.	Min.	Max.		
1	80 $\mu$ " Tin	120 $\mu$ " Tin Max. (Pre-tinned)	30 $\mu$ " Nickel	50 $\mu$ " Nickel Max. (Pre-tinned)	Overall	Crimp clip terminal
		120 $\mu$ " Tin Max. (Post Plating)		50 $\mu$ " Tin Max. (Post Plating)	Contact Area	
	100 $\mu$ " Tin	140 $\mu$ " Tin Max (Pre-tinned)	30 $\mu$ " Nickel	50 $\mu$ " Nickel Max. (Pre-tinned)	Overall	Solder tail terminal & Board in terminal
		160 $\mu$ " Tin Max (Post Plating)		50 $\mu$ " Tin Max. (Post Plating)	Contact Area	
	120 $\mu$ " Tin	190 $\mu$ " Tin Max.	30 $\mu$ " Nickel	50 $\mu$ " Nickel Max.	Contact Area	Square or round pin
	120 $\mu$ " Tin	170 $\mu$ " Tin Max (Pre-tinned)	50 $\mu$ " Nickel	70 $\mu$ " Nickel Max. (Pre-tinned)	Contact Area	SMT type terminal
		190 $\mu$ " Tin Max (Post Plating)		70 $\mu$ " Tin Max. (Post Plating)		

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**TABLE- 2 (Gold -Plated)**

Plating Code	Top Plating Thickness	Under Plating Thickness		Area	Match Type
		Min.	Max.		
2	Gold Flash Min.	50 $\mu$ " Nickel	70 $\mu$ " Nickel	Contact Area	All type
3	15 $\mu$ " Gold Min.	50 $\mu$ " Nickel	70 $\mu$ " Nickel	Contact Area	All type
4	30 $\mu$ " Gold Min.	50 $\mu$ " Nickel	70 $\mu$ " Nickel	Contact Area	All type
A	Selective Gold Flash	50 $\mu$ " Nickel		Contact Area	All type
B	Selective 15 $\mu$ " Gold	50 $\mu$ " Nickel		Contact Area	All type
C	Selective 30 $\mu$ " Gold	50 $\mu$ " Nickel		Contact Area	All type

**4. SOLDERABILITY:**

TEST ITEM	TEST CONDITION	PROCESS	TEST REQUIREMENT
Solder ability	Soldering time: 5 $\pm$ 0.5 Second Soldering pot: 230 $\pm$ 5 $^{\circ}$ C	Sn - Pb Process	Minimum: 95% of immersed area
	Soldering time: 3 $\pm$ 0.5 Second Soldering pot: 245 $\pm$ 5 $^{\circ}$ C	Lead Free Process	